

FRONT EDGE CHAMFER FEATURE FOR FULLY-MOLDED MEMORY CARDS

ABSTRACT OF THE INVENTION

[0026] A memory card comprising a leadframe having a plurality of contacts. Electrically connected to the leadframe is at least one semiconductor die. A body at least partially encapsulates the leadframe and includes opposed top and bottom surfaces, an opposed pair of longitudinal sides, and an opposed pair of lateral sides. Each of the contacts of the leadframe is exposed in the bottom surface of the body and includes a chamfer portion which extends to one of the lateral sides thereof.